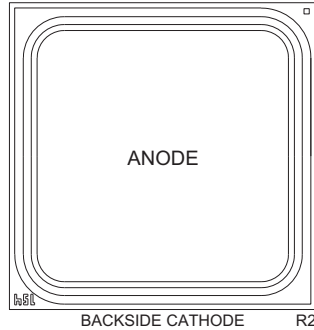


CPD77X-CTLSH3-30

Schottky Rectifier Die

3.0 Amp, 30 Volt

The CPD77X-CTLSH3-30 is a silicon Schottky rectifier designed for applications where operational efficiency is a prime requirement.



MECHANICAL SPECIFICATIONS:

Die Size	60.6 x 60.6 MILS
Die Thickness	5.9 MILS
Anode Bonding Pad Size	55 x 55 MILS
Top Side Metalization	Ti/Ag – 2,500Å/30,000Å
Back Side Metalization	Ti/Ni/Au – 1,600Å/5,550Å/1,500Å
Scribe Alley Width	2.4 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	4,616

MAXIMUM RATINGS: (T_A=25°C)

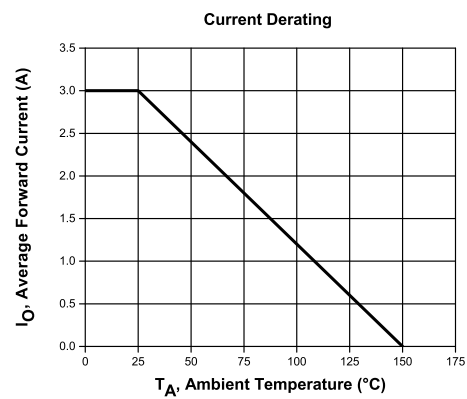
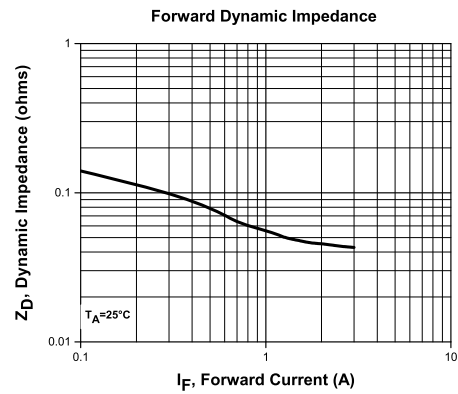
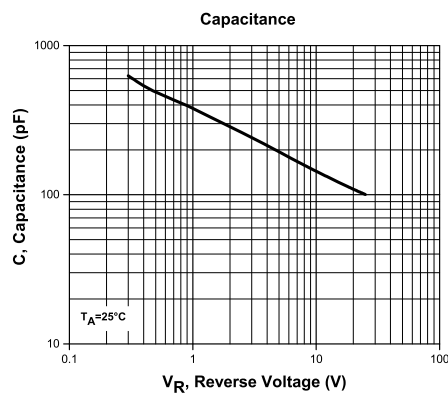
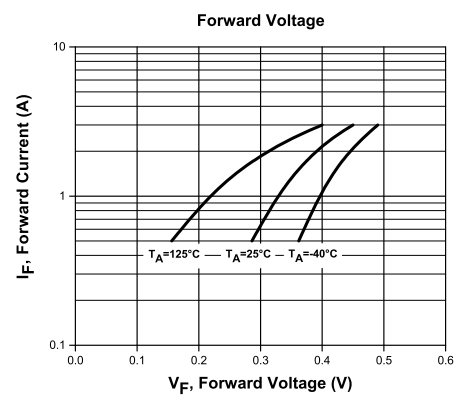
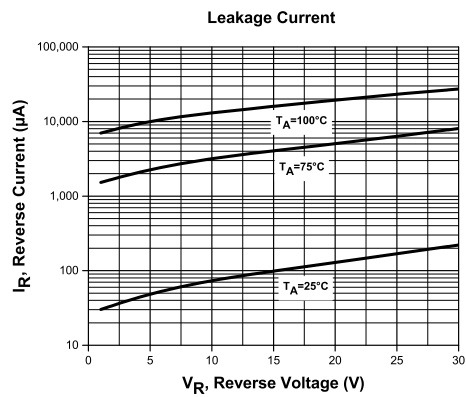
	SYMBOL		UNITS
Continuous Reverse Voltage	V _R	30	V
Average Forward Current	I _O	3.0	A
Peak Forward Surge Current, tp=8.3ms	I _{FSM}	25	A
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _R	V _R =30V		1.0	mA
BV _R	I _R =5.0mA	30		V
V _F	I _F =500mA		0.30	V
V _F	I _F =1.0A		0.35	V
V _F	I _F =2.0A		0.40	V
V _F	I _F =3.0A		0.45	V
C _J	V _R =1.0V, f=1.0MHz		450	pF

CPD77X-CTLSH3-30

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

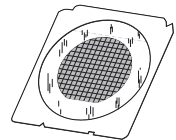
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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